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# FDN371N

# 20V N-Channel PowerTrench® MOSFET

# **General Description**

This 20V N-Channel MOSFET uses Fairchild's high voltage PowerTrench process. It has been optimized for power management applications.

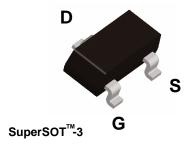
### **Applications**

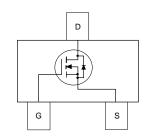
- Load switch
- Battery protection
- Power management

### **Features**

• 2.5 A, 20 V.  $R_{DS(ON)} = 50 \ m\Omega \ @ \ V_{GS} = 4.5 \ V$   $R_{DS(ON)} = 60 \ m\Omega \ @ \ V_{GS} = 2.5 \ V$ 

- Low gate charge (7.6 nC typical)
- · Fast switching speed
- High performance trench technology for extremely low R<sub>DS(ON)</sub>





# Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
$V_{DSS}$	Drain-Source Voltage		20	V
$V_{GSS}$	Gate-Source Voltage		± 12	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	2.5	А
	– Pulsed		10	
P <sub>D</sub>	Power Dissipation for Single Operation	(Note 1a)	0.5	W
		(Note 1b)	0.46	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		−55 to +150	°C

# **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W

# **Package Marking and Ordering Information**

Device Marking	Device	Reel Size	Tape width	Quantity
371	FDN371N	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics					ı
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250  \mu\text{A}$	20			V
ΔBV <sub>DSS</sub> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$ , Referenced to 25°C		13		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 16 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage, Forward	V <sub>GS</sub> = 12 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage, Reverse	$V_{GS} = -12 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)		•		•	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	0.5	1.0	1.5	V
$\Delta V_{GS(th)} \over \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu A$ , Referenced to 25°C		-3		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On–Resistance	$V_{GS} = 4.5 \text{ V}, \qquad I_D = 2.5 \text{ A}$ $V_{GS} = 2.5 \text{ V}, \qquad I_D = 2.3 \text{ A}$ $V_{GS} = 4.5 \text{ V}, I_D = 2.5 \text{ A}, T_J = 125^{\circ}\text{C}$		22 29 31	50 60 75	mΩ
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 5 V	5			Α
<b>g</b> FS	Forward Transconductance	$V_{DS} = 5V$ , $I_{D} = 2.5 \text{ A}$		16		S
Dvnamio	Characteristics		•	•	•	
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$		815		pF
Coss	Output Capacitance	f = 1.0 MHz		197		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	7		106		pF
	g Characteristics (Note 2)		ı			
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, \qquad I_D = 1 \text{ A},$		7	14	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		9	18	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			17	31	ns
t <sub>f</sub>	Turn-Off Fall Time			5.5	11	ns
Qg	Total Gate Charge	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 2.5 \text{ A},$		7.6	10.7	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 4.5 V		1.5		nC
$Q_{gd}$	Gate-Drain Charge	1		2		nC
Drain-Se	ource Diode Characteristics	and Maximum Ratings				ı
I <sub>s</sub>	Maximum Continuous Drain–Source				0.42	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_S = 0.42 \text{ A}  \text{(Note 2)}$		0.6	1.2	V

#### Notes

R<sub>QUA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>QUC</sub> is guaranteed by design while R<sub>QCA</sub> is determined by the user's board design.



a) 250°C/W when mounted on a 0.02 in² pad of 2 oz. copper.



b) 270°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

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# **Typical Characteristics**

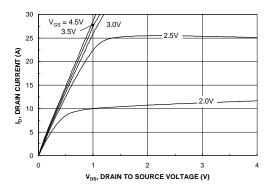


Figure 1. On-Region Characteristics.

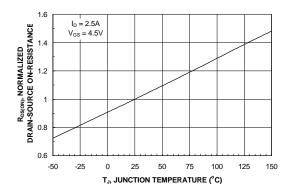


Figure 3. On-Resistance Variation with Temperature.

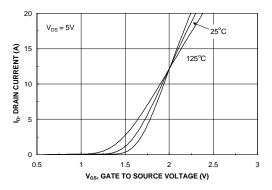


Figure 5. Transfer Characteristics.

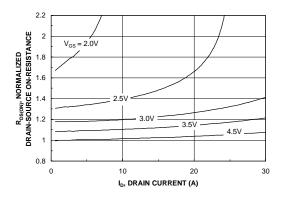


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

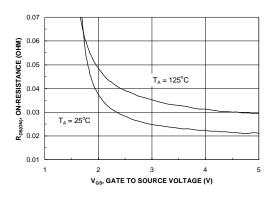


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

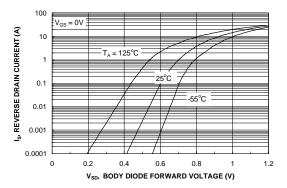
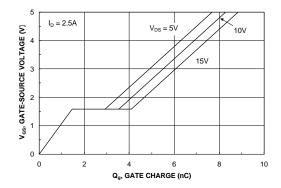


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

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# **Typical Characteristics**



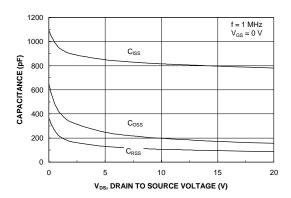


Figure 7. Gate Charge Characteristics.

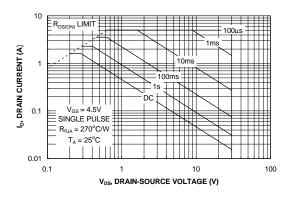
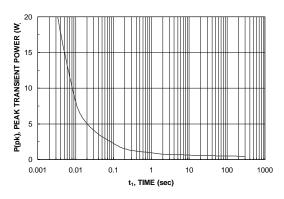


Figure 8. Capacitance Characteristics.



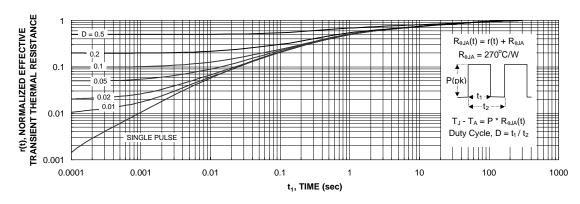


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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